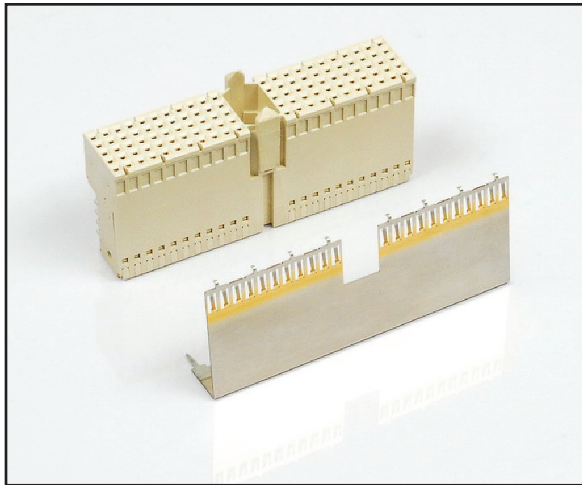


3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



- 25mm basic system unit
- 50mm module
- Designed according to IEC 61076-4-101 and IEC 60352-5 Standards
- 2 mm grid spacing allows for high signal density at low cost
- “Eye of the Needle” compliant pin press-fit design reduces manufacturing time and cost
- Additional grounding row available for improved ground bounce and EMI immunity
- Mates with 5 row 3M™ MetPak™ HM, and CP2 headers
- End-to-end stackable with 5 row 3M™ MetPak™ HSHM, HM, and CP2 sockets
- See Regulatory Information Appendix (RIA) for chemical compliance information

Date Modified: February 15, 2008

TS-2266-A
Sheet 1 of 2

Physical

Insulation:

Material: High Temperature Thermoplastic (LCP)

Flammability: UL94V-0

Contact:

Material: Copper Alloy

Plating: See Ordering Information

Mechanical

Mating Force: $\leq 0.75\text{N/PIN}$

Withdrawl Force: $\geq 0.15\text{N/PIN}$

Mating and Un-mating Operations: 50

Electrical

Contact Resistance: $\leq 20\text{ m}\Omega$

Insulation Resistance: $\geq 10,000\text{ M}\Omega$

Test Voltage: $750\text{ VAC}_{\text{RMS}}$

Environmental

Temperature Ratings: -55°C to $+125^{\circ}\text{C}$

PCB Data

Recommended PCB Plated Through Hole: $\Phi 0.6\pm 0.05\text{ mm}$

Drill Hole Diameter: $\Phi 0.7\pm 0.02\text{ mm}$

Hole platings: Cu 25~50 μm , Sn or SnPb < 10 μm

PCB thickness: 1.4-4.2 mm

Press-In Force: $\leq 204\text{N/pin}$ on nominal hole diameter

Retention Force: $\geq 13.5\text{N/pin}$ on nominal hole diameter

3M

Electronic Solutions Division
Interconnect Solutions

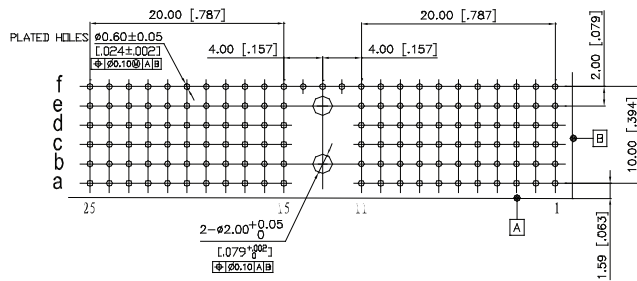
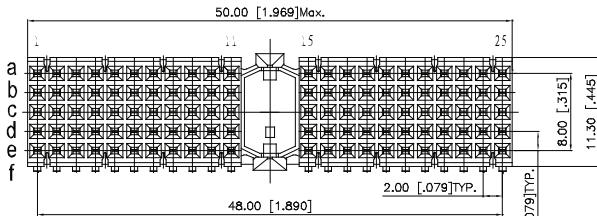
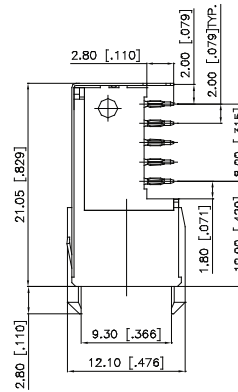
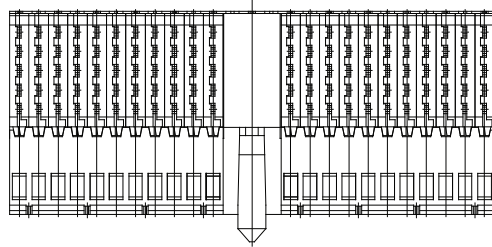
<http://www.3M.com/interconnects/>

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800-225-5373

3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



Recommended PCB Layout

Tolerance Unless Noted			
	mm	[Inch]	
	0.	.0	.00
mm	1	0.3	0.13

[] Dimensions for Reference only

Ordering Information

CP2-SA110-X1-XXXX

Shield Options
 G= Upper Shield
 Blank= No Shield

Plating Options

TG30= 30~40 μm Gold Contact Area
 100~200 μm Bright Tin-Lead
 50~80 μm Nickel Underplate
 (RIA E2 & C2 apply)
 FJ= 10~20 μm Gold Contact Area
 200~300 μm Matte Tin
 50~80 μm Nickel Underplate
 (RIA E1 & C1 apply)
 KR= 30~40 μm Gold Contact Area
 200~300 μm Matte Tin
 50~80 μm Nickel Underplate
 (RIA E1 & C1 apply)

• This diagram serves only for Part Number descriptive definitions.

PLEASE CONTACT YOUR LOCAL SALES REPRESENTATIVE FOR CUSTOMER SPECIFIC PRODUCT CONFIGURATIONS.

TS-2266-A
 Sheet 2 of 2

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